

BRCS26N50PA

Rev.A Jan.-2019

Parameter	Symbol	Rating	Unit
Drain Source Voltage	V_{DSS}	500	V

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V$ $I_D=250\mu A$	500			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=500V$ $V_{GS}=0V$			1	μA
Gate- Source Leakage Current Forward	I_{GSSF}	$V_{DS}=0V$ $V_{GS}=+30V$			+100	nA
Gate-Source Leakage Current Reverse	I_{GSSR}	$V_{DS}=0V$ $V_{GS}=-30V$			-100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=250\mu A$	3.0		5.0	V
Static Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V$ $I_D=13A$		0.17	0.2	
Input Capacitance	C_{iss}	$V_{DS}=25V$ $V_{GS}=0V,$ $f=1.0MHz$		3360		pF
Output Capacitance	C_{oss}			280		
Reverse Transfer Capacitance	C_{rss}			35		
Total Gate Charge		$V_{GS}=10V$ $V_{DS}=400V$ $I_D=26A$ (Note 1, 2)		81	120	nC
Gate to Source Charge				23		
Gate to Drain Charge				35		
	$t_{D(ON)}$	$V_{DD}=250V$ $I_D=26A$ $R_G=25$ (Note 1, 2)		80	170	ns
Rise Time	t_R			2500	500	
Turn-OFF Delay Time	$t_{D(OFF)}$			200	400	
Fall-Time	t_F			155	320	
Maximum Body-Diode Continuous Current	I_S				26	A
Maximum Body-Diode Pulsed Current	I_{SM}				104	A
Drain-Source Diode Forward Voltage	V_{SD}	$I_S=26A$ $V_{GS}=0V$			1.4	V
Body Diode Reverse Recovery Time	T_{rr}	$I_S=26A$ $V_{GS}=0V$ $dI_F/dt=100A/\mu s$ (Note 1)		530		ns
Body Diode Reverse Recovery Charge	Q_{RR}				8.2	μC

1. $300\mu s$ 2%

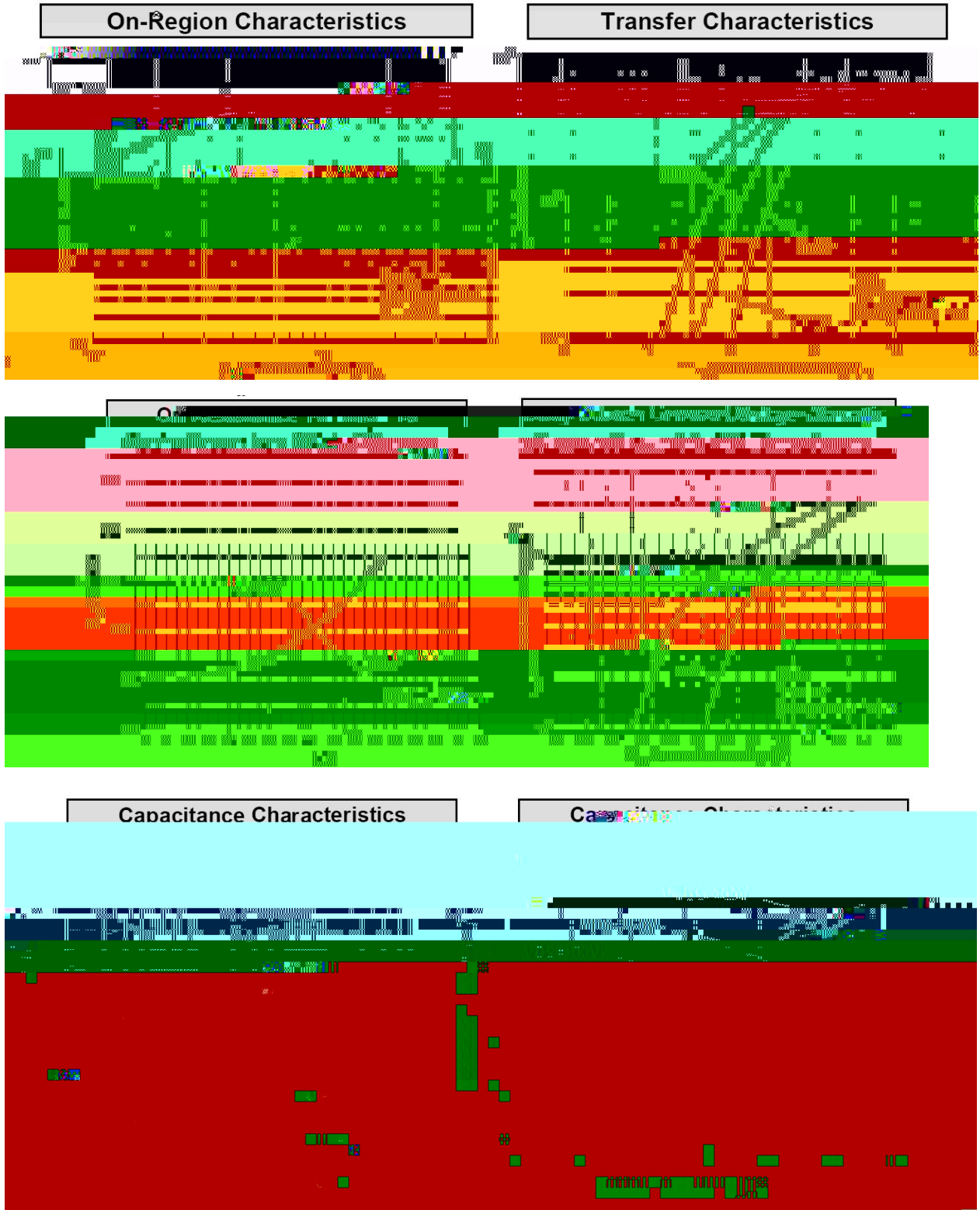
2.

ote:

1. Pulse Test: Pulse width $300\mu s$, Duty cycle 2%.

2. Essentially independent of operating temperature.

/ Electrical Characteristic Curve

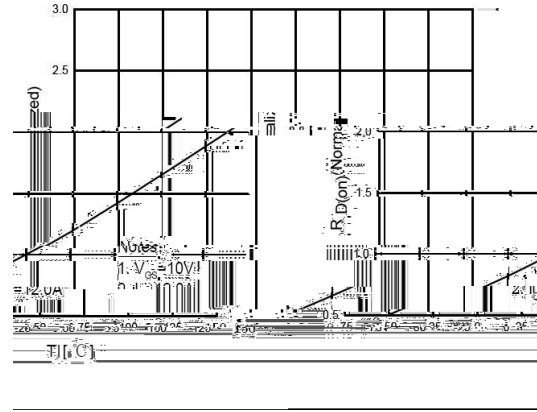


/ Electrical Characteristics(Ta=25)

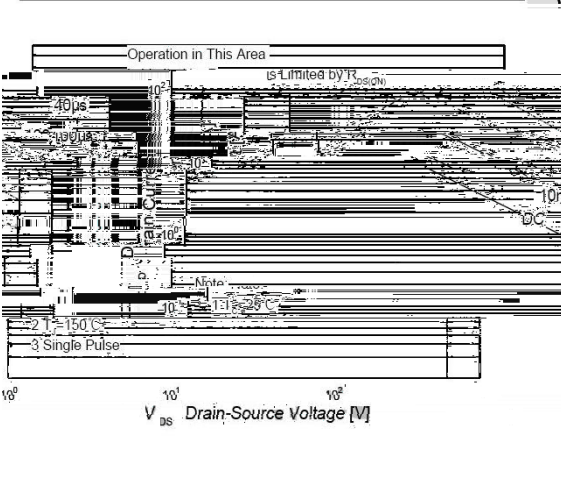
Breakdown Voltage Variation



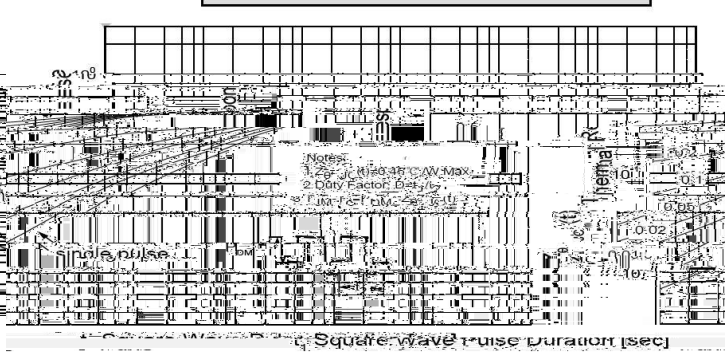
On-Resistance Variation vs. Temperature



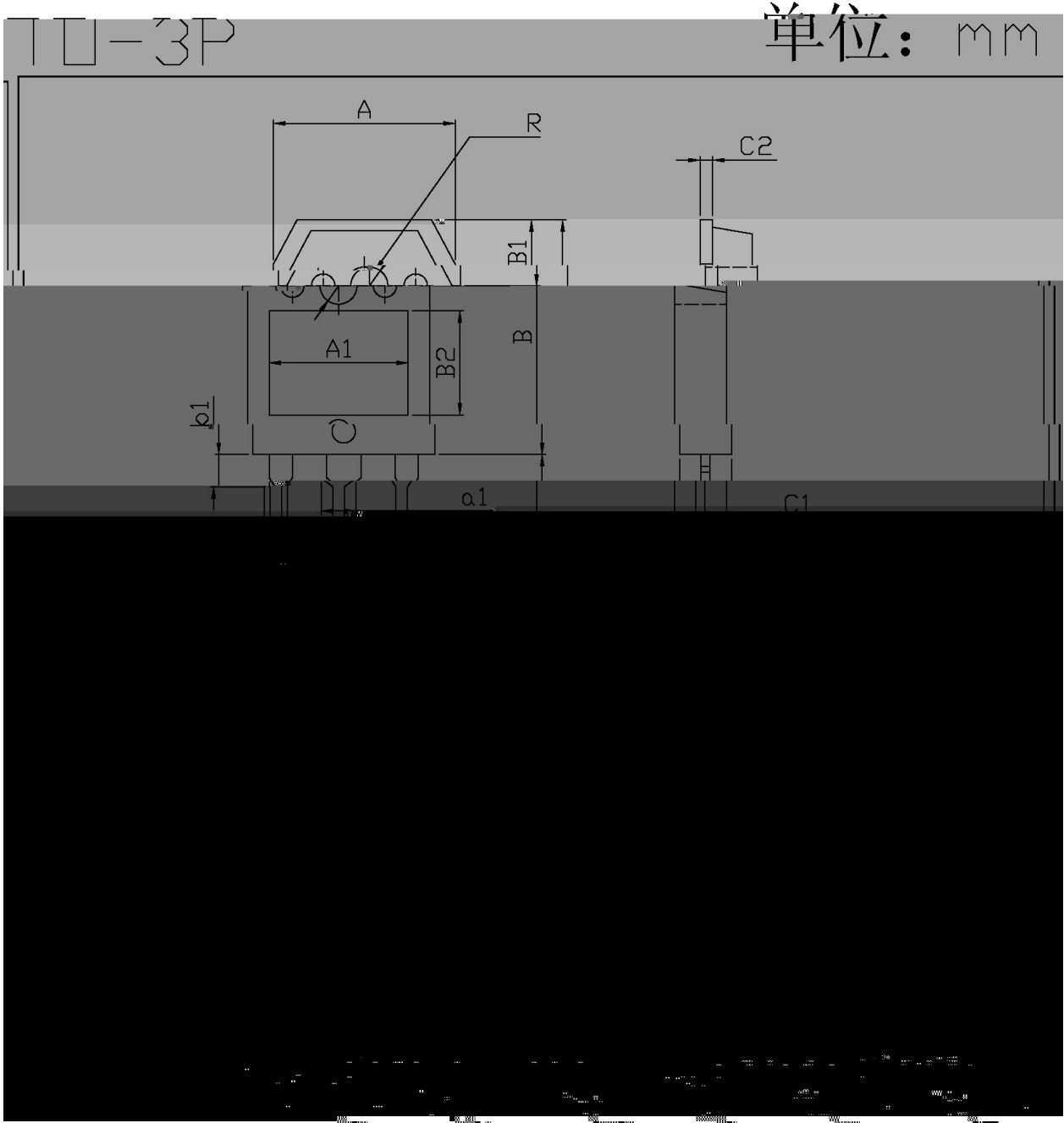
Maximum Safe Operating Area



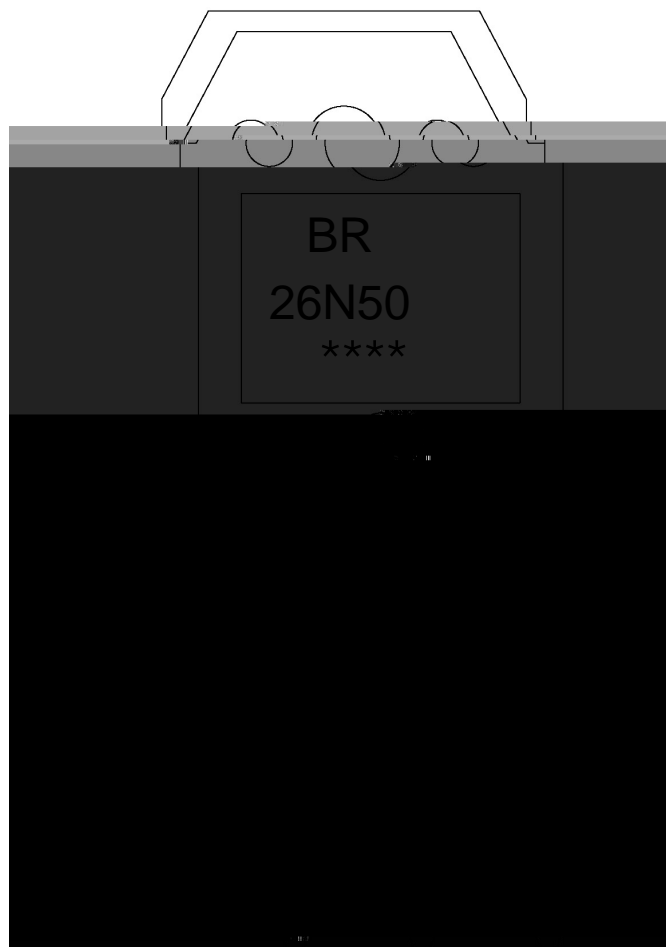
Transient Thermal Response Curve



/ Package Dimensions



/ Marking Instructions



BR:

26N50

Note:

BR: Company Code.

26N50: Product Type.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱